

N-SGT Enhancement Mode MOSFET

## **General Description**

The HNTTFS5C471NLTAG use advanced SGT MOSFET

technology to provide low RDS(ON), low gate charge,

fast switching and excellent avalanche characteristics

This device is specially designed to get better ruggedness.



DFN3X3-8L

### **General Features**

V<sub>DS</sub> =40V I<sub>D</sub> =60 A

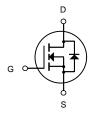
 $R_{DS(ON)}$  < 8.5m $\Omega$ @  $V_{GS}$ =10V



Consumer electronic power supply Motor control

Synchronous-rectification Isolated DC

Synchronous-rectification applications



N-Channel MOSFET

### **Package Marking and Ordering Information**

Product ID	Pack	Brand	Qty(PCS)
HNTTFS5C471NLTAG	DFN3X3-8L	HXY MOSFET	5000

### Absolute Maximum Ratings at T<sub>j</sub>=25°C unless otherwise noted

Parameter	Symbol	Value	Unit
Drain source voltage	VDS	40	V
Gate source voltage	VGS	±20	V
Continuous drain current <sup>1)</sup>	ID	60	Α
Pulsed drain current <sup>2)</sup>	ID, pulse	130	А
Power dissipation <sup>3)</sup>	P <sub>D</sub>	39	W
Single pulsed avalanche energy <sup>5)</sup>	EAS	48	mJ
Operation and storage temperature	Tstg, Tj	-55 to 150	℃
Thermal resistance, junction-case	RθJC	3.2	°C/W
Thermal resistance, junction-ambient <sup>4)</sup>	RθJA	60	°C/W

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### Electrical Characteristics (T<sub>J</sub>=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	40			V
Dagan	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}$ =10V , $I_D$ =12A		6.9	8.5	m()
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	V <sub>GS</sub> =4.5V , I <sub>D</sub> =10A		10.0	15	mΩ
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}$ , $I_D=250uA$	1.35		3	V
	Drain-Source Leakage Current	V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	uA
I <sub>DSS</sub>		V <sub>DS</sub> =32V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	
Igss	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.7		Ω
Qg	Total Gate Charge (4.5V)			5.8		
Qgs	Gate-Source Charge	V <sub>DS</sub> =20V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =12A		3		nC
Q <sub>gd</sub>	Gate-Drain Charge			1.2		
T <sub>d(on)</sub>	Turn-On Delay Time			14.3		
Tr	Rise Time	$V_{DD}$ =15V , $V_{GS}$ =10V , $R_{G}$ =3.3 $\Omega$		5.6		
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =1A		20		ns
T <sub>f</sub>	Fall Time			11		
Ciss	Input Capacitance			690		
Coss	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		193		pF
C <sub>rss</sub>	Reverse Transfer Capacitance			38		

### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current <sup>1,5</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			60	Α
$V_{SD}$	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1	V

#### Note:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper. 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%

- 3.The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V, $V_{GS}$ =10V,L=0.1mH, $I_{AS}$ =31A 4.The power dissipation is limited by 150°C junction temperature 5.The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications , should be limited by total power dissipation.



## **Typical Characteristics**

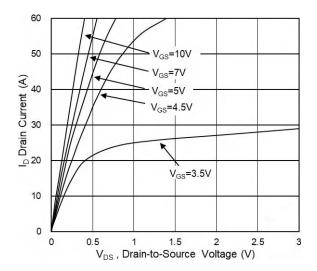


Fig.1 Typical Output Characteristics

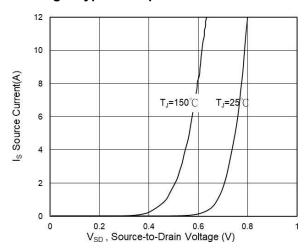


Fig.3 Source Drain Forward Characteristics

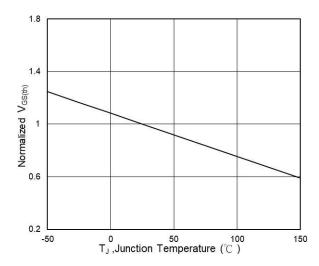


Fig.5 Normalized  $V_{GS(th)}vs\ T_J$ 

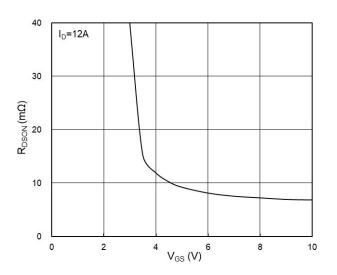


Fig.2 On-Resistance vs G-S Voltage

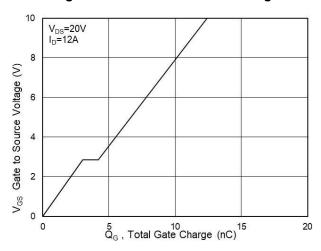


Fig.4 Gate-Charge Characteristics

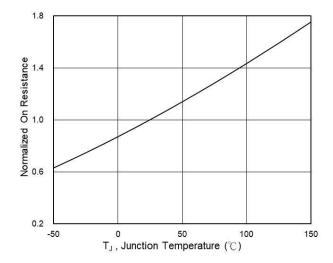
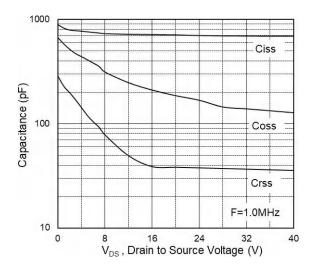


Fig.6 Normalized R<sub>DSON</sub> vs T<sub>J</sub>



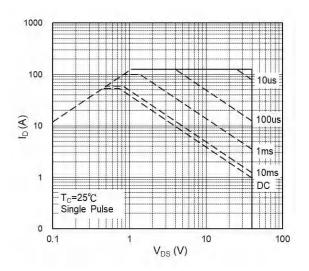
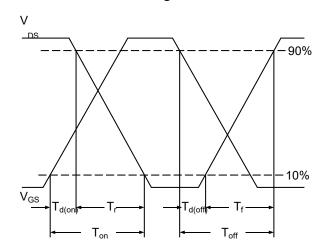


Fig.7 Capacitance Fig.8 Safe Operating Area Normalized Thermal Response (R⊌c) DUTY=0.5 0.3 0.1 0.05  $P_{\text{DM}}$ 0.02 0.01  $D = T_{ON}/T$  $T_J peak = T_C + P_{DM} x R_{\theta JC}$ SINGLE PULSE 0.01 0.00001 0.0001 0.001 0.01 0.1 t, Pulse Width (s)

Fig.9 Normalized Maximum Transient Thermal Impedance



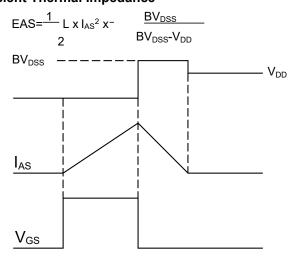
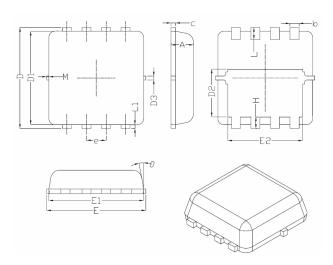


Fig.11 Unclamped Inductive Waveform

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### **DFN3X3-8L Package Information**



Sumb al	Dimensions In Millimeters			
Symbol	Min.	Nom.	Max.	
A	0.70	0.75	0.80	
b	0.25	0.30	0.35	
С	0.10	0.15	0.25	
D	3.25	3.35	3.45	
D1	3.00	3.10	3.20	
D2	1.48	1.58	1.68	
D3	-	0.13	-	
E	3.20	3.30	3.40	
E1	3.00	3.15	3.20	
E2	2.39	2.49	2.59	
е	0.65BSC			
Н	0.30	0.39	0.50	
L	0.30	0.40	0.50	
L1	-	0.13	-	
M	*	*	0.15	
θ		10°	12 <sup>°</sup>	

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